## **MA2SD10**

### Silicon epitaxial planar type

For super high speed switching

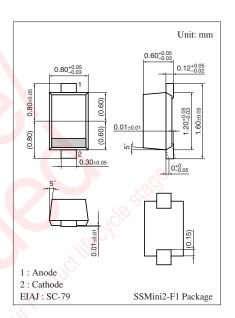
#### Features

- Forward current (Average)  $I_{F(AV)} = 200 \text{ mA}$  rectification is possible
- Low forward voltage V<sub>F</sub>
- High-density mounting is possible

#### ■ Absolute Maximum Ratings T<sub>a</sub> = 25°C

Parameter	Symbol	Rating	Unit	
Reverse voltage	$V_R$	20	V	
Repetitive peak reverse voltage	V <sub>RRM</sub>	20	V	
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	A	
Peak forward current	$I_{FM}$	300	mA	
Forward current (Average)	I <sub>F(AV)</sub>	200	mA	
Junction temperature	$T_{j}$	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

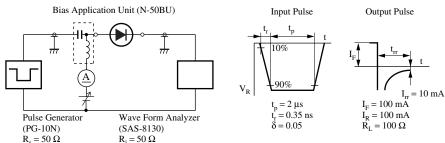


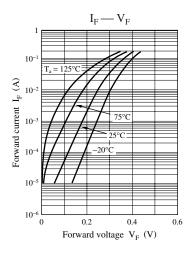
Marking Symbol: 2L

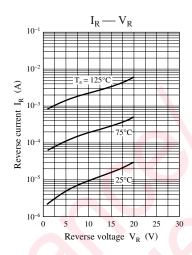
#### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min T	ур Мах	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 5 \text{ mA}$	272	0.27	V
	$V_{F2}$	$I_F = 100 \text{ mA}$		0.40	
	$V_{F3}$	I <sub>F</sub> = 200 mA	0)	0.47	
Reverse current	$I_R$	$V_R = 10 \text{ V}$		20	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$	2	5	pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$	3	3	ns
"allo		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$			

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Absolute frequency of input and output is 250 MHz.
  - 4. \*: t<sub>rr</sub> measurement circuit







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